

# VUSB003R520NA

**Datasheet** 





### VUSB003R520NA

## **General Description**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)_max</sub>	$I_D$
30V	52mΩ@10V	
	65mΩ@4.5V	4.0A
	85mΩ@2.5V	

## **Symbol**

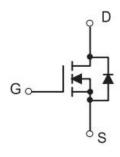


Figure 1 Symbol of VUSB003R520NA

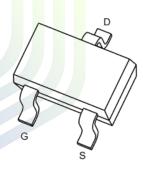
### **Features**

- Trench Technology Power MOSFET
- $\blacksquare$  Low  $R_{DS(on)}$
- Low Gate Charge

## **Application**

- DC/DC Converter
- Load Switch for Portable Devices
- Battery Switch

## Package Type



**SOT-23** 

Figure 2 Package Type of VUSB003R520NA

## **Ordering Information**

Product Name	Package		
VUSB003R520NA	SOT-23		



### VUSB003R520NA

## Absolute Maximum Ratings (T<sub>A</sub>= 25 °C, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{ m DSS}$	30	V
Gate-Source Voltage	$V_{GSS}$	±12	V
Continuous Drain Current Note1 T <sub>A</sub> = 25	°C I <sub>D</sub>	4	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	15	A
Total Power Dissipation $^{Note4}$ $T_A = 25$	C P <sub>D</sub>	1.5	W
Junction Temperature	$T_{\mathrm{J}}$	150	°C
Storage Temperature	T <sub>STG</sub>	-55 to 150	°C

### **Thermal Resistance**

Par <mark>ameter                                   </mark>	Symbol	<mark>M</mark> in	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient Note5	$R_{ heta JA}$		83.3		°C/W





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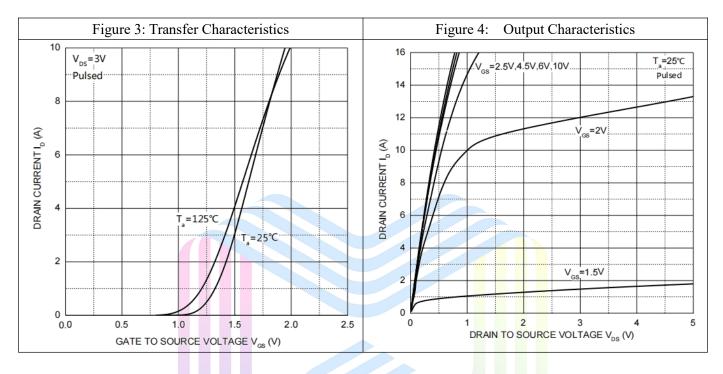
## Electrical Characteristics (T<sub>A</sub>= 25 °C, unless otherwise specified)

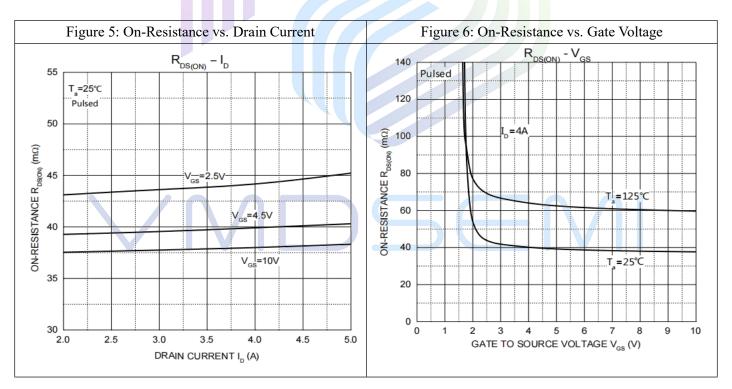
Parameter	Symbol	<b>Test Conditions</b>	Min	Тур	Max	Unit	
Statistic Characteristics							
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250uA$ 30				V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> =0V			1	uA	
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 12V, V_{DS} = 0V$			±100	nA	
Gate Threshold Voltage <sup>Note3</sup>	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_D=250uA$ 0.5		0.95	1.5	V	
		$V_{GS} = 10V, I_D = 4A$		34	52		
Static Drain-Source On-Resistance <sup>Note3</sup>	R <sub>DS(ON)</sub>	$V_{GS}$ = 4.5V, $I_{D}$ = 3A		37	65	mΩ	
		$V_{GS}$ = 2.5V, $I_{D}$ = 2A		45	85		
Forward tranconductance <sup>Note3</sup>	$g_{\mathrm{FS}}$	$V_{DS} = 5V, I_D = 3.6A$		13		S	
Dynamic Characteristics							
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =15V		389		pF	
Output Capacitance	Coss	V <sub>GS</sub> =0V		54		pF	
Reverse Transfer Capacitance	C <sub>RSS</sub>	f=1MHz		40		pF	
Total Gate charge	Qg	V <sub>DS</sub> =15V		4.4			
Gate-source charge	$Q_{gs}$	V <sub>GS</sub> =4.5V		0.7		nC	
Gate-drain charge	Q <sub>gd</sub>	$I_D=4A$		1.3			
Gate Resistance	Rg	f = 1MHz,open drain		3.5		Ω	
Switching Parameters							
Turn-on Delay Time	t <sub>d(on)</sub>	$V_{DD}=15V$		3.5			
Turn-on Rise Time	t <sub>r</sub>	$V_{GS}=10V$		1.2			
Turn-off Delay Time	t <sub>d(off)</sub>	$R_L=3.75\Omega$		22		ns	
Turn-off Fall Time	$t_{\mathrm{f}}$	$R_G=6\Omega$		2.2			
Source - Drain Diode Characteristics							
Diode Forward Voltage Note3	$V_{SD}$	$V_{GS} = 0V$ , $I_S = 1A$			1.0	V	
Continuous Source-Drain Diode Current	$I_{S}$	$T_{\rm C}=25~{\rm ^{\circ}C}$			1.5	A	
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> =4A		1.3		ns	
Body diode reverse recovery charge	Qrr	dI/dt=100A/μs		6.2		nC	

#### Notes:

- 1. The maximum current rating is limited by package.
- 2. Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3. Pulse Test : Pulse Width  $\leq 300 \mu s$ , duty cycle  $\leq 2\%$ .
- 4. The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150$ °C.
- 5.Device mounted on  $1 \text{in}^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^{\circ}\text{C}$ .

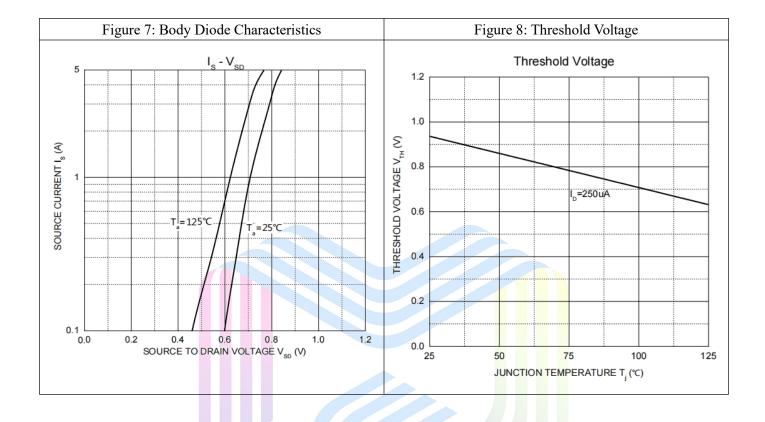
## **Typical Performance Characteristics**







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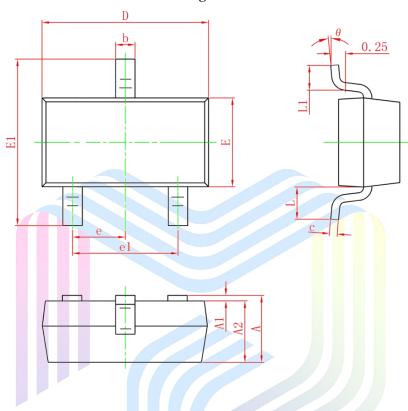






## **Mechanical Dimensions:**

**SOT-23 Package Information** 



Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Syllibol	Min.	Max.	Min.	Max.	
Α	0.900	1.150	0.035	0.045	
A1	0	0.100	0	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
C	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.150	1.500	0.045	0.059	
E1	2.250	2.650	0.089	0.104	
е	0.950TYP		0.037	7TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550REF		L 0.550REF 0.022REF		2REF
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	



### 52mΩ, 30V, N-Channel Power MOSFET

#### VUSB003R520NA

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